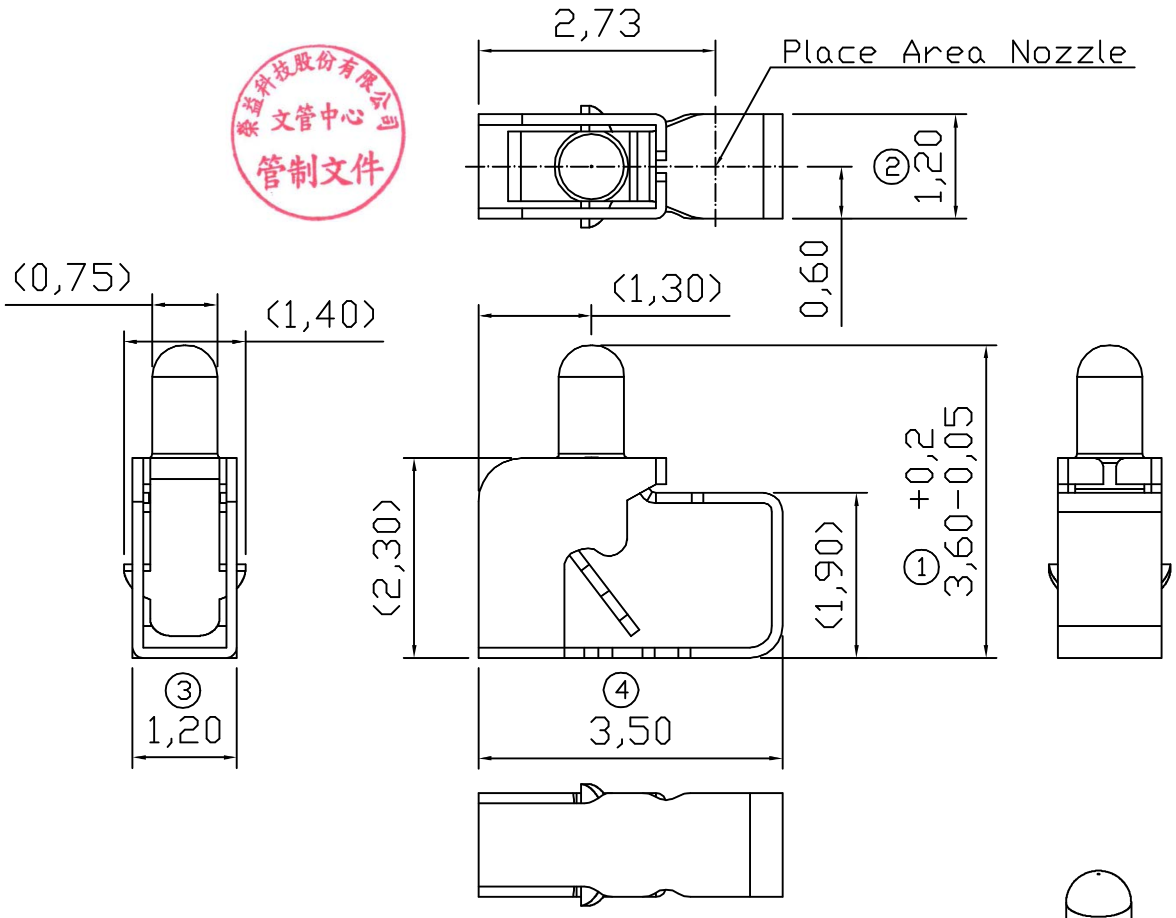
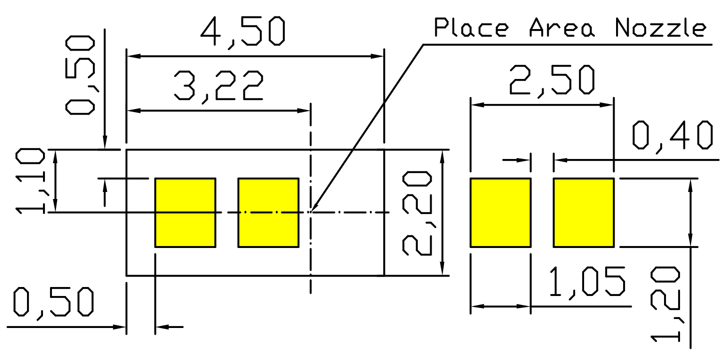
00	12/04-'14

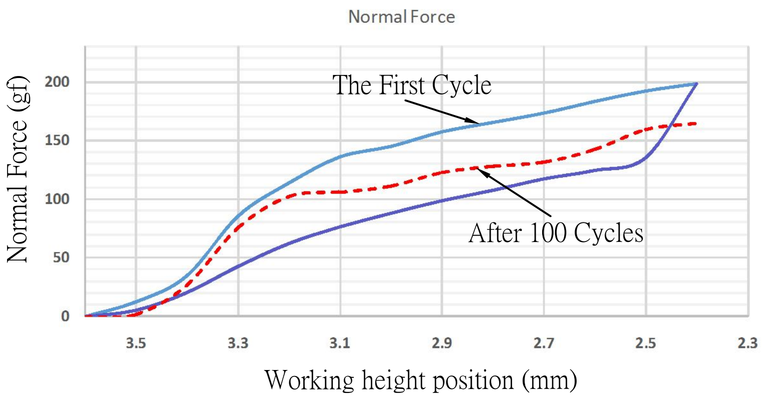
榮益科技股份有限公司
文管中心
管制文件

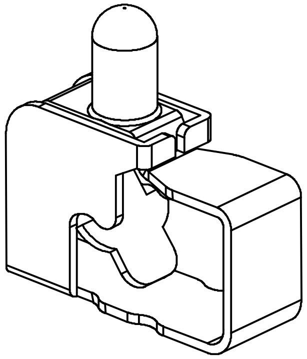




RECOMMENDED SOLDERING PCB LAYOUT

TOLERANCE(.XX±0.05)





Note:
1. Material: Beryllium Copper Thickness 0.12mm
2. Electroplate:
    Gold Flash on contact area
    Gold Flash on solder area
    Nickel underplating over all
3.Electrical Characteristics:
  3-1 Current Voltage: 12V
  3-2 Current Rate: 3A
  3-3 Contact Resistance: Normal Compression<30mΩ
4.Working Height of Application: 2.40~3.20 mm
5.Spring Force Tolerance is ±20gf
6.Operating Temperature: -20℃~+85℃

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<- ≤120	±0.15	0.20	0.30
120<- ≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

REV	Date	Description
00	11/20-'14	Design creation

DRAFT Roy Li	DATE 11/20-'14	RoHS Compatible			
CHECKER Justin Wu	DATE 11/20-'14				
APPROVAL Jacky Lin	DATE 11/20-'14	SHEET 1-2	SCALE Not to scale	UNIT mm	

EMI STOP
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EMISTOP QQ-36G	CUS P/N